

Material Declaration Report



Package Type:	BQSOP 40L
Pericom Package Code:	B40(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	164.500
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	12/2/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)			
MOLD COMPOUND	102.279	OSE	Silica Fused	60676-86-0	90.800	92.8693			
			Epoxy Resin 1	Proprietary	3.000	3.0684			
			Phenolic Resin	Proprietary	3.000	3.0684			
			Epoxy Resin 2	Proprietary	2.000	2.0456			
			Aromatic Phosphate	Proprietary	1.000	1.0228			
			Carbon Black	1333-86-4	0.200	0.2046			
			Silica Fused	60676-86-0	88.000	90.0055			
		SPEL	Epoxy Resin	Proprietary	5.000	5.1140			
			Phenolic Resin	Proprietary	4.500	4.6026			
			Epoxy, Cresol Novolac	29690-82-2	2.000	2.0456			
			Carbon Black	1333-86-4	0.500	0.5114			
			LEADFRAME	54.979		Copper	7440-50-8	97.021	53.3411
						Iron	7439-89-6	2.350	1.2920
						Silver	7440-22-4	0.453	0.2492
Zinc	7440-66-6	0.111				0.0609			
Phosphorus	7723-14-0	0.065				0.0357			
SILICON DIE	2.647		Silicon (Si)	7440-21-3	99.192	2.6256			
			Non-hazardous Metal	Proprietary	0.808	0.0214			
DIE ATTACH EPOXY	0.281	OSE	Silver	7440-22-4	76.000	0.2136			
			Acrylic Resin	Proprietary	8.000	0.0225			
			Acrylate	Proprietary	5.500	0.0155			
			Polybutadiene derivative	Proprietary	5.500	0.0155			
			Epoxy resin	Proprietary	2.500	0.0070			
			Additive	Proprietary	1.000	0.0028			
			Butadiene copolymer	Proprietary	1.000	0.0028			
		Peroxide	Proprietary	0.500	0.0014				
		SPEL	Silver	7440-22-4	80.000	0.2248			
			Epoxy Resin	9003-36-5	10.000	0.0281			
			Diluent	26447-14-3	6.000	0.0169			
			Hardener	620-92-8	3.250	0.0091			
			Dicyandamide	461-58-5	0.750	0.0021			
			GOLD WIRE	0.675		Gold(Au)	7440-57-5	99.990	0.6749
Impurities	-					0.010	0.0001		
SOLDER PLATING	3.639		Tin (Sn)	7440-31-5	99.990	3.6386			
			Impurity	-	0.010	0.0004			

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													
O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.																		